

FORM PTO-1596

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DOCKET NO.: 4425-233

101927002 PATENTS ONLY U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto: 2. Name and address of receiving party(ies): 1. Name of conveying party(ies): Name: UNITED MICROELECTRONICS CORP Kun-Chih WANG Internal Address: Additional name(s) of conveying party(ies) attached? MEISTA 3. Nature of conveyance: Street Address: No. 3, Li-Hsin Rd. 2, Science-Based Industrial X Assignment Park Change of Name Security Agreement Taiwan City: **Hsin-Chu City** State or Area: Other R.O.C. Zip/Postal Code: Country: Additional name(s) & address(es) attached? Execution Date: November 28, 2001 4. Application number(s) or patent number(s): If the document is being filed together with a new application, the execution date of the application is: November 28, 2001 B. Patent No(s). A. Patent Application No(s). 10020311 Additional numbers attached? 6. Total number of applications and patents involved: one 5. Name and address of party to whom correspondence concerning document should be mailed: \$40.00 7. Total fee (37 CFR 3.41) Name: LOWE HAUPTMAN GILMAN & BERNER ☐ Authorized to be charged to deposit account Internal Address: 8. Deposit account number: 07-1337 Street Address: 1700 Diagonal Road, Suite 310 ZIP: 22314 State: VA City: Alexandria DO NOT USE THIS SPACE To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the 9. Statement and signature. original document. Benjamin J. Haupting December 18, 2001 Date Total number of pages comprising cover sheet: 2 CMB No. 0851-0011 (exp. 4/94)

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PATENT REEL: 012393 FRAME: 0007

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

Kun-Chih WANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

UNITED MICROELECTRONICS CORP.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

FUSE STRUCTURE INTEGRATED WIRE BONDING ON THE LOW K INTERCONNECT AND METHOD FOR MAKING THE SAME

- for which an application for United States Letters Patent was filed on, and identified by United States Serial No.; or [a]
- [b] for which an application for United States Letters Patent was executed on,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS

DATE SIGNED

Name: Kun-Chih WANG

RECORDED: 12/18/2001

REEL: 012393 FRAME: 0008